

# **DATASHEET**

# 6 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER CNY17-X Series CNY17F-X Series







#### Features:

Current transfer ratios in selected narrow range groups
 ONN(77 to 000)(77 to 000)

CNY17-1, CNY17F-1: 40-80%

CNY17-2, CNY17F-2: 63-125%

CNY17-3, CNY17F-3: 100-200%

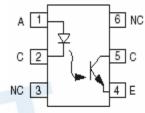
CNY17-4, CNY17F-4:160-320%

- High isolation voltage between input and output (Viso = 5000 Vrms)
- Creepage distance > 7.6 mm
- Operating temperature up to +110°C
- The CNY17F-X series offers no external base connection for minimum noise susceptibility
- Compact dual-in-line package
- •The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

#### Schematic

# A 1 6 B C 2 5 C

# Schematic



CNY17-X

#### Pin Configuration

- 1. Anode
- 2. Cathode
- 3. No Connection
- 4. Emitter
- 5. Collector
- 6. Base

# Pin Configuration

CNY17F-X

- 1. Anode
- 2. Cathode
- 3. No Connection
- 4. Emitter
- 5. Collector
- 6. No Connection

#### **Description**

The CNY17-X and CNY17F-X series of devices each consist of an infrared emitting diode optically coupled to a phototransistor.

They are packaged in a 6-pin DIP package and available in wide-lead spacing and SMD option.

### **Applications**

- · Power supply regulators
- Digital logic inputs
- Microprocessor inputs



# Absolute Maximum Ratings (Ta=25℃)

	Parameter	Symbol	Rating	Unit
	Forward current	I <sub>F</sub>	60	mA
	Peak forward current (t = 10µs)	I <sub>FM</sub>	1	А
Input	Reverse voltage	$V_{R}$	6	V
	Power dissipation (T <sub>A</sub> = 25°C)	P <sub>D</sub> —	100	mW
	Derating factor (above 100°C)	FD	3.8	mW/°C
Output	Collector-Emitter voltage	$V_{CEO}$	80	V
	Collector-Base voltage*1	$V_{CBO}$	80	V
	Emitter-Collector voltage	V <sub>ECO</sub>	7	V
	Emitter-Base voltage	V <sub>EBO</sub>	7	V
	Power dissipation ( $T_A = 25$ °C)	D -	150	mW
	Derating factor (above 100°C)	Pc —	9.0	mW/°C
Total Power Dissipation		Ртот	200	mW
Isolation voltage *2		V <sub>ISO</sub>	5000	V rms
Operating Temperature		T <sub>OPR</sub>	-55 to 110	°C
Storage Temperature		T <sub>STG</sub>	-55 to 125	°C
Soldering temperature *3		T <sub>SOL</sub>	260	°C

#### Notes:

<sup>\*1</sup> Only for CNY17-X series.

<sup>\*2</sup> AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 & 3 are shorted together, and pins 4, 5 & 6 are shorted together.

<sup>\*3</sup> For 10 seconds.



# Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	V <sub>F</sub>	-	-	1.65	V	I <sub>F</sub> = 60mA
Reverse current	$I_R$	-	-	10	μΑ	$V_R = 6V$
Input capacitance	C <sub>in</sub>	-	18	-	pF	V = 0, f = 1MHz

Output

Paramet	Symbol	Min	Тур.	Max.	Unit	Condition	
Collector-Base dark current	CNY17-X only	: I <sub>CBO</sub>	-	-	20	nA	$V_{CB} = 10V, I_F = 0mA$
Collector-Emitter dark current		I <sub>CEO</sub>		-	50	nA	V <sub>CE</sub> = 10V, IF=0mA
Collector-Emitter breakdown voltage		BV <sub>CEO</sub>	80	-	-	V	$I_C = 1mA$ , $I_F = 0mA$
Collector-Base breakdown voltage	CNY17-X only	ВУсво	80	16		V	$I_C = 0.1 \text{mA},$ $I_F = 0 \text{mA}$
Emitter-Collector breakdown voltage		BV <sub>ECO</sub>	7	11.0		V	$I_E = 0.1 \text{mA},$ $I_F = 0 \text{mA}$
Collector-Emitter ca	CCE		8	-	pF	VCE = 0V, f =1MHz	

<sup>\*</sup> Typical values at T<sub>a</sub> = 25°C



### **Transfer Characteristics**

Pa	arameter	Symbol	Min	Тур.	Max.	Unit	Condition	
	CNY17-1 CNY17F-1	— - CTR - — -	40	-	80	%		
Current Transfer	CNY17-2 CNY17F-2		63	-	125		I <sub>F</sub> = 10mA ,V <sub>CE</sub> = 5V	
Ratio	CNY17-3 CNY17F-3		100	-	200		IF = TOTTIA, VCE = OV	
	CNY17-4 CNY17F-4		160	-	320			
	CNY17-1 CNY17F-1		13	-	-	%		
Current Transfer	CNY17-2 CNY17F-2	— CTR - — -	22	-	-		$I_F = 1 \text{mA}$ , $V_{CE} = 5 \text{V}$	
Ratio	CNY17-3 CNY17F-3		34	-	-			
	CNY17-4 CNY17F-4		56	-	-			
Collector-Emitter saturation voltage		$V_{\text{CE(sat)}}$	-	-	0.3	V	$I_F = 10 \text{mA}$ , $I_C = 2.5 \text{mA}$	
Isolation resistance		R <sub>IO</sub>	1011	-	-	Ω	V <sub>IO</sub> = 500Vdc	
Input-outpu	Input-output capacitance		-	0.5		pF	$V_{IO} = 0$ , $f = 1MHz$	
Turn-on tim	е	Ton	-	10	12			
Turn-off time		$T_{off}$	39-1	9	12		$V_{CC} = 10V$ ,	
Rise time		Tr	7.1	6	10		$I_C$ = 2mA, $R_L$ = 100 $\Omega$ See Fig. 11	
Fall time		T <sub>f</sub>	-	8	10	μs		
Rise time		Tr	-	2	10		$V_{CC} = 5V, I_F = 10mA,$	
Fall time		$T_f$	-	3	10		$R_L = 75\Omega$ , See Fig. 11	

<sup>\*</sup> Typical values at T<sub>a</sub> = 25°C



# **Typical Electro-Optical Characteristics Curves**

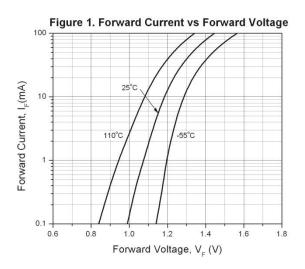


Figure 2. Current Tranfer Ratio vs Forward Current

1.2

0.6

0.7

0.7

0.7

1.0

0.8

V<sub>cE</sub>=5 V

Ta=25°C

Normalized to I<sub>F</sub>=10 mA

Forward Current, I<sub>E</sub> (mA)

Figure 3. Current Tranfer Ratio vs Ambient Temperature

1.4  $V_{ce}$  =5V Normalized to  $I_p$  =10 mA, Ta = 25 °C  $I_p$  =20 mA  $I_p$  =10 mA

1.0  $I_p$  =10 mA

1.1  $I_p$  =10 mA

1.2  $I_p$  =10 mA

1.3  $I_p$  =10 mA

1.4  $I_p$  =10 mA

1.5  $I_p$  =10 mA

1.6  $I_p$  =10 mA

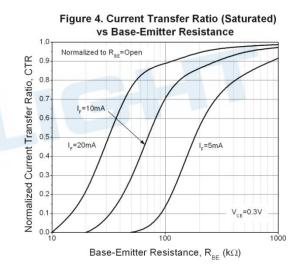
1.7  $I_p$  =10 mA

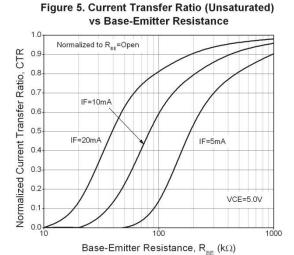
1.8  $I_p$  =10 mA

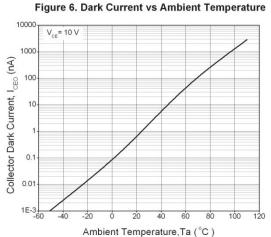
1.9  $I_p$  =10 mA

1.9  $I_p$  =10 mA

1.0  $I_p$  =10







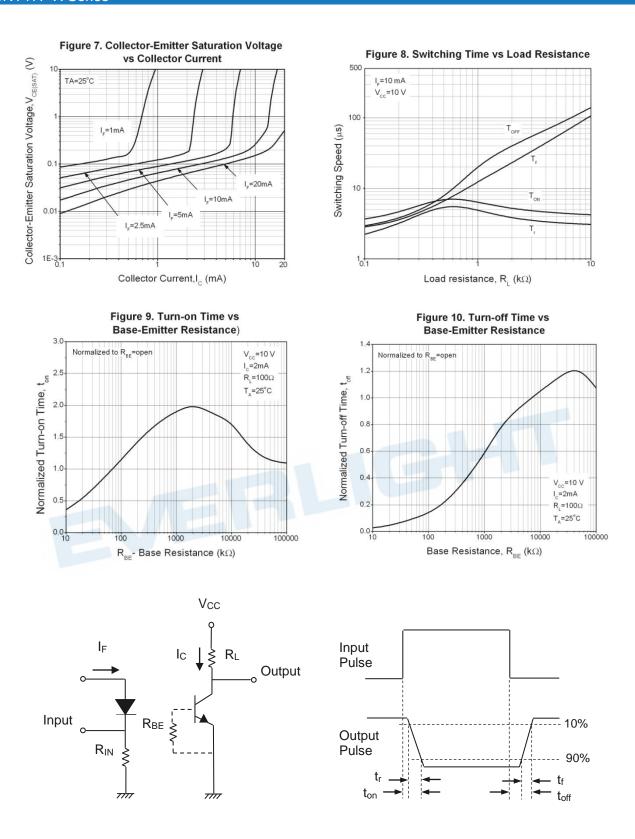


Figure 11. Switching Time Test Circuit & Waveforms



#### **Order Information**

#### **Part Number**

or CNY17-XY(Z)-V

#### Note

X = Part no. (1, 2, 3 or 4)

Y = Lead form option (S, S1, M or none)

Z = Tape and reel option (TA, TB or none).

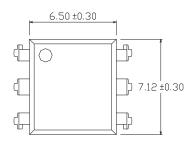
V = VDE (optional)

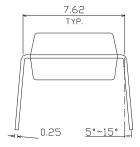
Option	Description	Packing quantity
None	Standard DIP-6	65 units per tube
М	Wide lead bend (0.4 inch spacing)	65 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

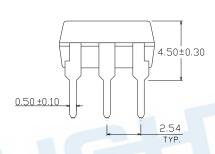


# Package Dimension (Dimensions in mm)

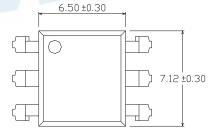
### **Standard DIP Type**

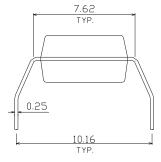


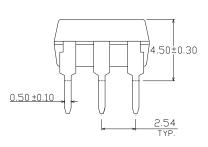




# **Option M Type**

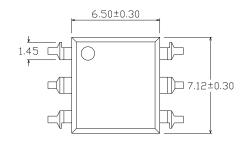


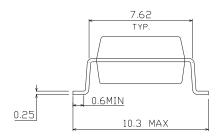


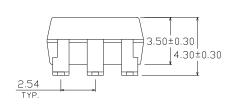




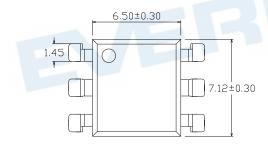
# **Option S Type**

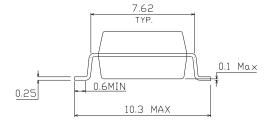


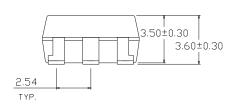




# **Option S1 Type**

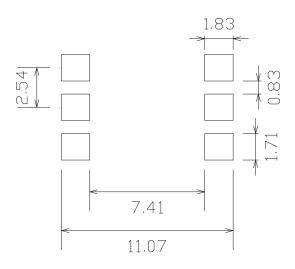








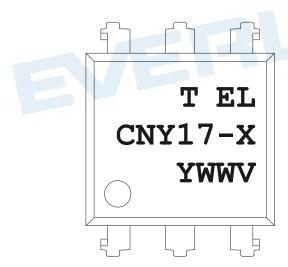
# Recommended pad layout for surface mount leadform



#### **Notes**

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

# **Device Marking**



#### **Notes**

T denotes Factory

No code : made in China

T: made in Taiwan

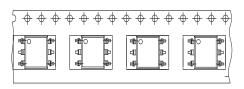
EL denotes Everlight

CNY17-X denotes Device Number (X: 1, 2, 3 or 4)

Y denotes 1 digit Year code WW denotes 2 digit Week code V denotes VDE (optional)

**Tape & Reel Packing Specifications** 

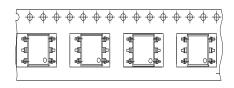
### **Option TA**





Direction of feed from reel

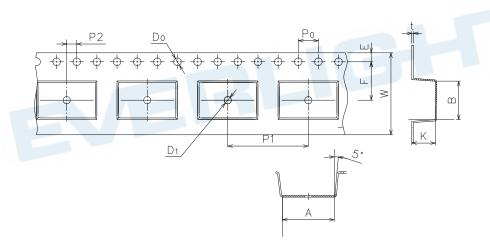
### **Option TB**





Direction of feed from reel

# **Tape dimensions**



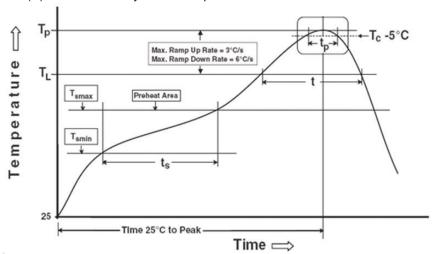
Dimension No.	Α	В	Do	D1	E	F
Dimension (mm)	10.8±0.1	7.55±0.1	1.5±0.1	1.5+0.1/-0	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	W	К
Dimension (mm)	4.0±0.15	12±0.1	2.0±0.1	0.35±0.03	16.0±0.2	4.5±0.1



#### **Precautions for Use**

#### 1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

#### **Preheat**

Temperature min (T<sub>smin</sub>)

Temperature max (T<sub>smax</sub>)

Time (T<sub>smin</sub> to T<sub>smax</sub>) (t<sub>s</sub>)

Average ramp-up rate (T<sub>smax</sub> to T<sub>p</sub>)

Other

Liquidus Temperature (T<sub>L</sub>)

Time above Liquidus Temperature (t L)

Peak Temperature (T<sub>P</sub>)

Time within 5 °C of Actual Peak Temperature: TP - 5°C

Ramp- Down Rate from Peak Temperature

Time 25°C to peak temperature

Reflow times

Reference: IPC/JEDEC J-STD-020D

150 °C

200°C

60-120 seconds

3 °C/second max

217 °C

60-100 sec

260°C

30 s

6°C /second max.

8 minutes max.

3 times



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